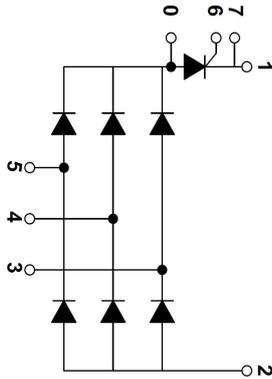


### PRODUCT FEATURES

- Isolated Module Package
- Isolation voltage 3000 V
- Three Phase Bridge and a Thyristor

### APPLICATIONS

- Current Stabilized Power Supply
- Switching Power Supply
- Inverter For AC or DC Motor Control



### ABSOLUTE MAXIMUM RATINGS (Thyristor)

$T_c=25^{\circ}\text{C}$  unless otherwise specified

| Symbol       | Parameter/Test Conditions             |  | Values      | Unit              |
|--------------|---------------------------------------|--|-------------|-------------------|
| $V_{RRM}$    | Repetitive Peak Reverse Voltage       |  | 1600        | V                 |
| $V_{DRM}$    | Repetitive Peak Off-State Voltage     |  | 1600        |                   |
| $V_{RSM}$    | Non-Repetitive Peak Reverse Voltage   |  | 1700        |                   |
| $I_{T(AV)}$  | Average On State Current              | Single phase, half wave, 180° conduction, $T_c=90^{\circ}\text{C}$ | 75          | A                 |
| $I_{T(RMS)}$ | R.M.S. On State Current               |  | 117         |                   |
| $I_{TSM}$    | Non-Repetitive Surge On-State Current | 1/2 cycle, 50/60HZ, peak value, $T_c=45^{\circ}\text{C}$           | 1500/1650   |                   |
| $i^2t$       | For Fusing                            | 1/2 cycle, 50/60HZ, peak value, $T_c=45^{\circ}\text{C}$           | 11.2/11.3   | KA <sup>2</sup> S |
| $T_J$        | Junction Temperature(Thyristor)       |  | -40 to +125 | °C                |

### ABSOLUTE MAXIMUM RATINGS (Three Phase Diode)

| Symbol    | Parameter/Test Conditions            |  | Values      | Unit              |
|-----------|--------------------------------------|--|-------------|-------------------|
| $V_{RRM}$ | Repetitive Peak Reverse Voltage      |  | 1600        | V                 |
| $V_{RSM}$ | Non-Repetitive Peak Reverse Voltage  |  | 1700        |                   |
| $I_D$     | Output Current(D.C.)                 | Three phase, half wave, $T_c=95^{\circ}\text{C}$         | 75          | A                 |
| $I_{FSM}$ | Non-Repetitive Surge Forward Current | 1/2 cycle, 50/60HZ, peak value, $T_c=45^{\circ}\text{C}$ | 1050/1150   |                   |
| $i^2t$    | For Fusing                           | 1/2 cycle, 50/60HZ, peak value, $T_c=45^{\circ}\text{C}$ | 5.5/5.49    | KA <sup>2</sup> S |
| $T_J$     | Junction Temperature(Diode)          |  | -40 to +150 | °C                |

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**ELECTRICAL CHARACTERISTICS (Thyristor)** $T_C = 25^\circ\text{C}$  unless otherwise specified

| Symbol        | Parameter/Test Conditions  |   | Min. | Typ. | Max. | Unit             |
|---------------|--|---|------|------|------|------------------|
| $I_{DRM}$     | Maximum Peak Off-State Current   | $V_D = V_{DRM}, T_J = 125^\circ\text{C}$              |      |      | 25   | mA               |
| $I_{RRM}$     | Maximum Peak Reverse Current   | $V_R = V_{RRM}, T_J = 125^\circ\text{C}$              |      |      | 25   |                  |
| $V_{TM}$      | Maximum on-state voltage drop  | $I_{TM}=250\text{A}, t_d=10\text{ ms, half sine}$     |      |      | 1.5  | V                |
| $V_{TO}$      | For power-loss calculations only   | $T_J = 125^\circ\text{C}$                             |      |      | 0.85 | V                |
| $r_T$         |  |   |      |      | 2.7  | m $\Omega$       |
| $V_{GT}$      | Max. required DC gate voltage to trigger   | $V_A=6\text{V}, R_A=1\Omega, T_J = -40^\circ\text{C}$ |      |      | 4.0  | V                |
|               |  | $V_A=6\text{V}, R_A=1\Omega$                          |      | 1.0  | 2.5  |                  |
|               |  | $V_A=6\text{V}, R_A=1\Omega, T_J = 125^\circ\text{C}$ |      |      | 1.7  |                  |
| $I_{GT}$      | Max. required DC gate current to trigger   | $V_A=6\text{V}, R_A=1\Omega, T_J = -40^\circ\text{C}$ |      |      | 270  | mA               |
|               |  | $V_A=6\text{V}, R_A=1\Omega$                          |      | 75   | 150  |                  |
|               |  | $V_A=6\text{V}, R_A=1\Omega, T_J = 125^\circ\text{C}$ |      |      | 80   |                  |
| $V_{GD}$      | Max. required DC gate voltage not to trigger,  | $V_D = V_{DRM}, T_J = 125^\circ\text{C}$              |      |      | 0.25 | V                |
| $I_{GD}$      | Max. required DC gate current not to trigger,  | $V_D = V_{DRM}, T_J = 125^\circ\text{C}$              |      |      | 6    | mA               |
| $I_H$         | Maximum holding current  |   |      | 100  | 200  | mA               |
| $I_L$         | Maximum latching current   |   |      | 200  | 400  | mA               |
| $P_{GM}$      | Maximum peak gate power  |   |      |      | 12   | W                |
| $P_{G(AV)}$   | Maximum average gate power   |   |      |      | 3.0  |                  |
| $I_{GM}$      | Maximum peak gate current  |   |      |      | 3.0  | A                |
| $-V_{GM}$     | Maximum peak negative gate voltage   |   |      |      | 10   | V                |
| $dv/dt$       | Critical Rate of Rise of Off-State Voltage, $T_J=125^\circ\text{C}$ , exponential to 67% rated $V_{DRM}$ |   |      |      | 1000 | V/ $\mu\text{s}$ |
| $di/dt$       | Max. Rate of Rise of Turned-on Current, $T_J = 125^\circ\text{C}, I_{TM}=250\text{A}$ , rated $V_{DRM}$  |   |      |      | 150  | A/ $\mu\text{s}$ |
| $R_{th(J-C)}$ | Junction-to-Case Thermal Resistance  |   |      |      | 0.3  | K /W             |

**ELECTRICAL CHARACTERISTICS (Three Phase Diode)**

| Symbol        | Parameter/Test Conditions                                    |  | Min. | Typ. | Max. | Unit       |
|---------------|--|--|------|------|------|------------|
| $I_{RM}$      | Maximum Reverse Leakage Current                              | $V_R = V_{RRM}$                          |      |      | 0.5  | mA         |
|               |  | $V_R = V_{RRM}, T_J = 125^\circ\text{C}$ |      |      | 10   |            |
| $V_F$         | Forward Voltage Drop   | $I_F=75\text{A}$                         |      |      | 1.35 | V          |
| $V_{TO}$      | For power-loss calculations only , $T_J = 125^\circ\text{C}$ |  |      |      | 0.93 | V          |
| $r_T$         |  |  |      |      | 5    | m $\Omega$ |
| $R_{th(J-C)}$ | Junction-to-Case Thermal Resistance                          | per diode                                |      |      | 0.9  | K /W       |
|               |  | per module                               |      |      | 0.15 |            |

## MODULE CHARACTERISTICS

$T_C=25^{\circ}\text{C}$  unless otherwise specified

|           |                             |                            |             |                    |
|-----------|-----------------------------|----------------------------|-------------|--------------------|
| $T_J$     | Junction Temperature        |                            | -40 to +125 | $^{\circ}\text{C}$ |
| $T_{STG}$ | Storage Temperature Range   |                            | -40 to +125 | $^{\circ}\text{C}$ |
| $V_{ISO}$ | Isolation Breakdown Voltage | AC, 50Hz(R.M.S), t=1minute | 3000        | V                  |
| Torque    | to heatsink                 | Recommended (M6)           | 3~5         | Nm                 |
|           | to terminal                 | Recommended (M5)           | 2.5~5       | Nm                 |
| Weight    |                             |                            | 215         | g                  |

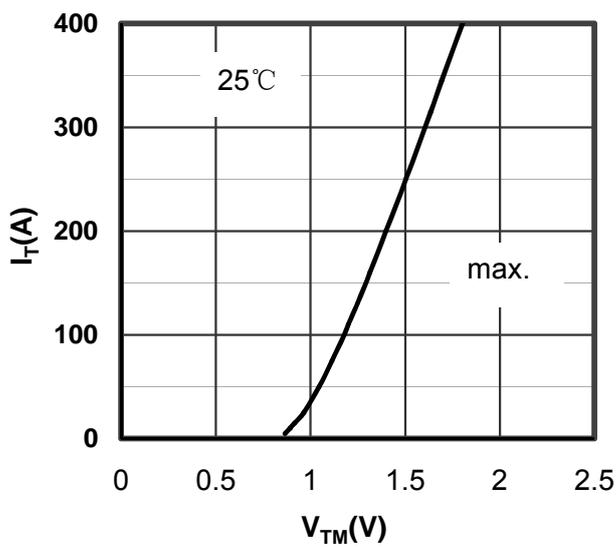


Figure1. Forward Voltage Drop vs Forward Current

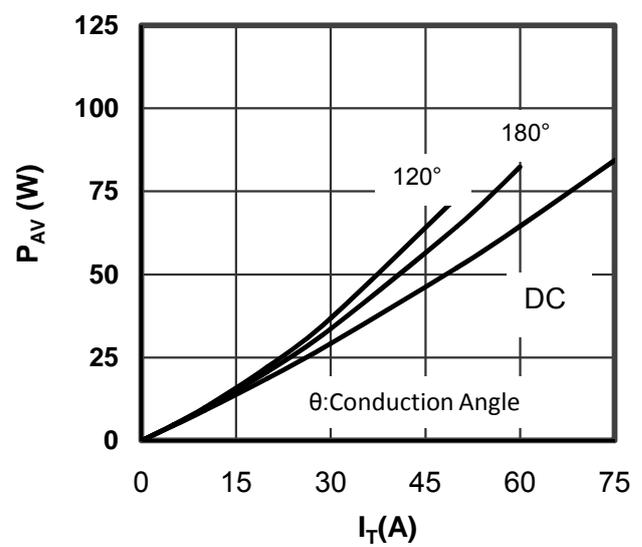


Figure2. Power dissipation vs.  $I_T$

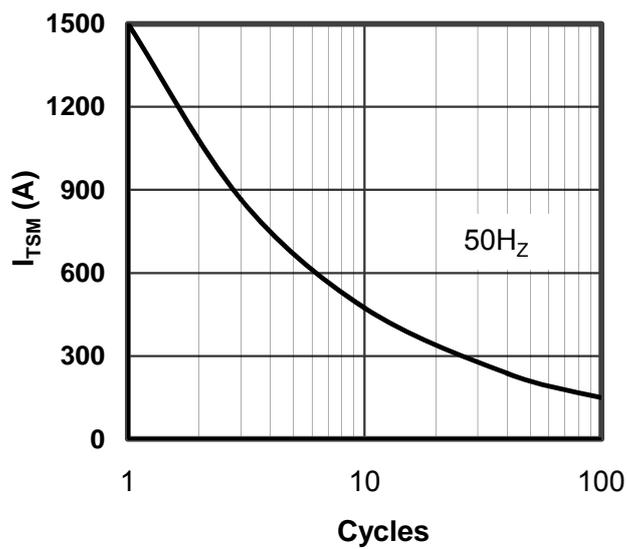


Figure3. SCR Max Non-Repetitive Surge Current

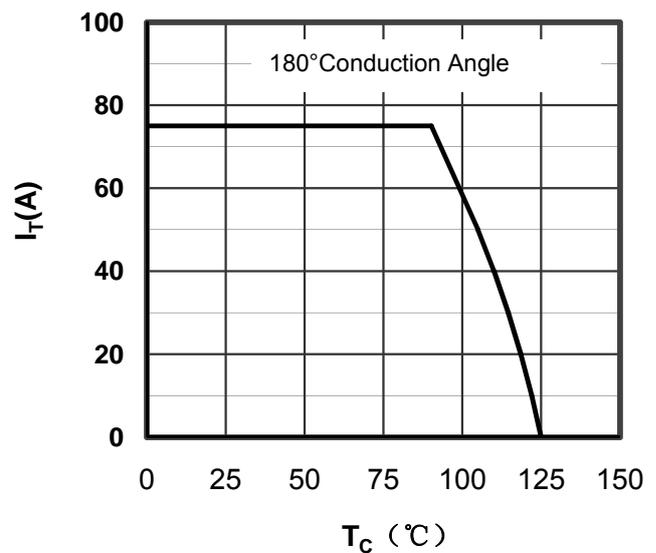


Figure4. SCR  $I_{T(AV)}$  vs.  $T_C$

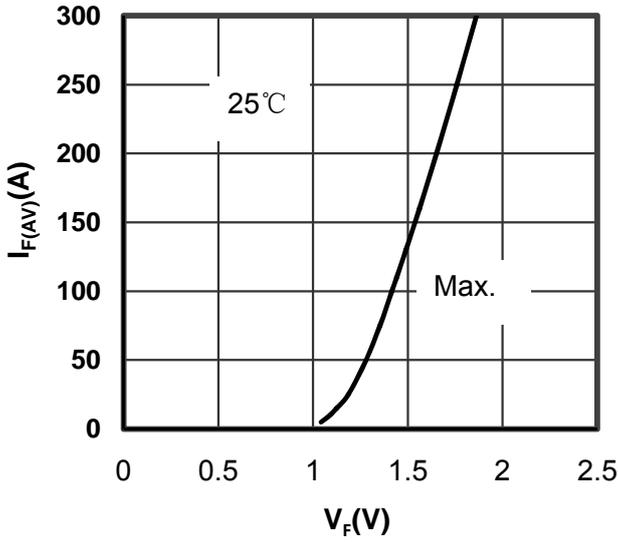


Figure5. Forward Voltage Drop vs Forward Current

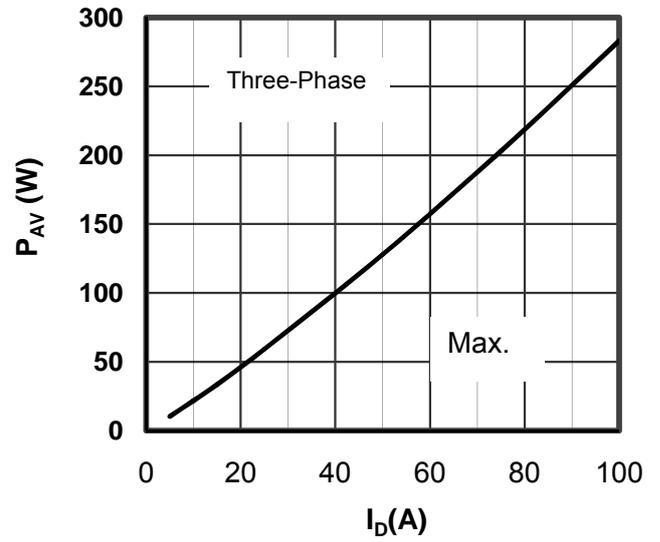


Figure6. Power dissipation vs.  $I_D$

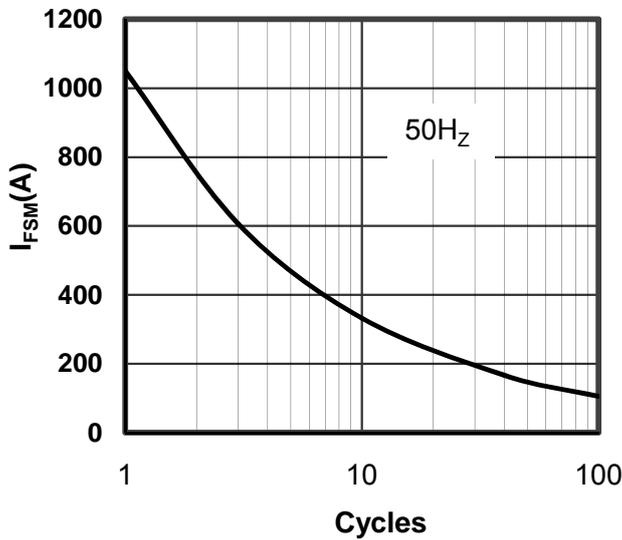


Figure7. Diode Max Non-Repetitive Surge Current

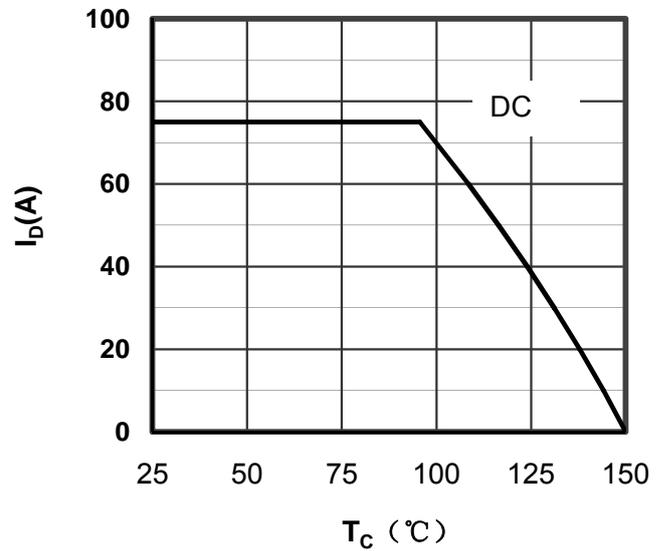


Figure8. Output current vs. Case temperature

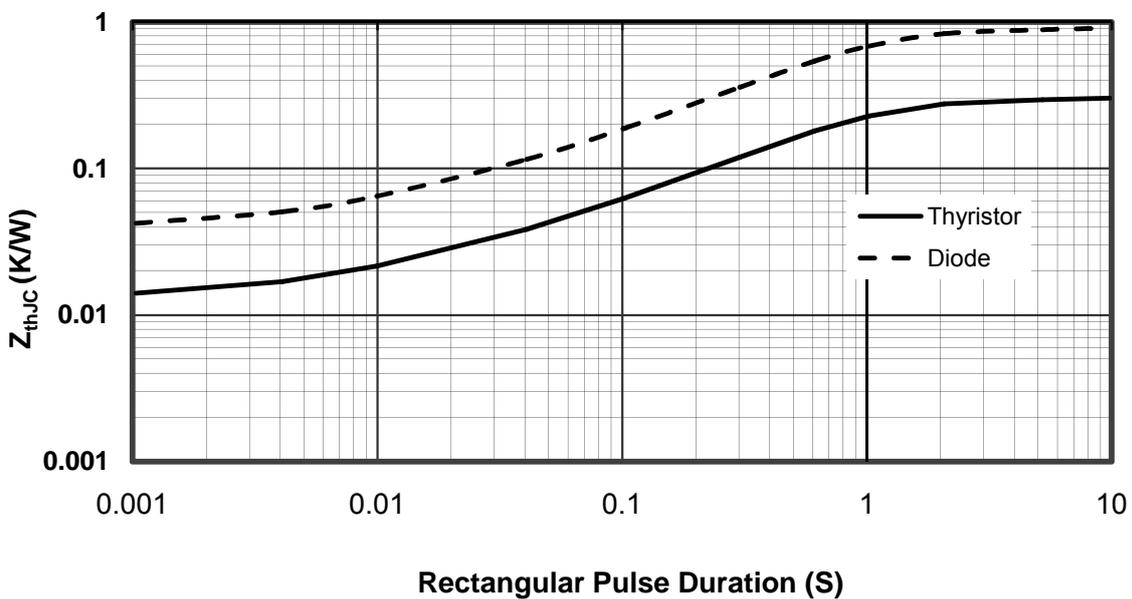


Figure9. Transient Thermal Impedance of Per Diode and SCR

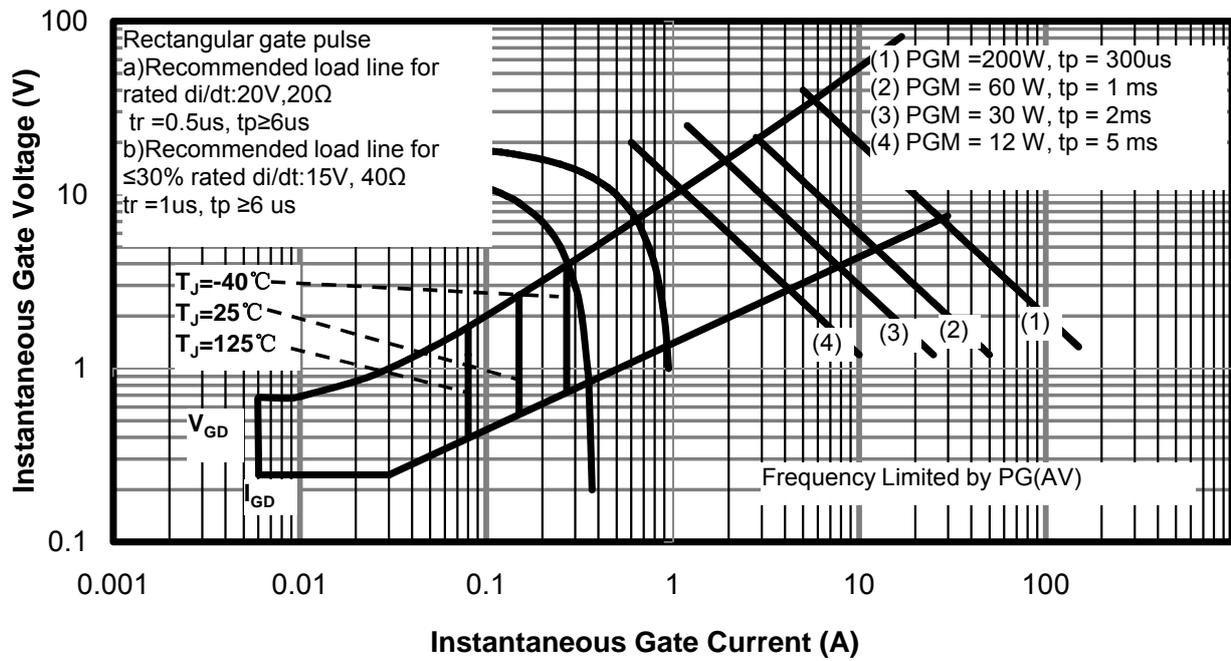
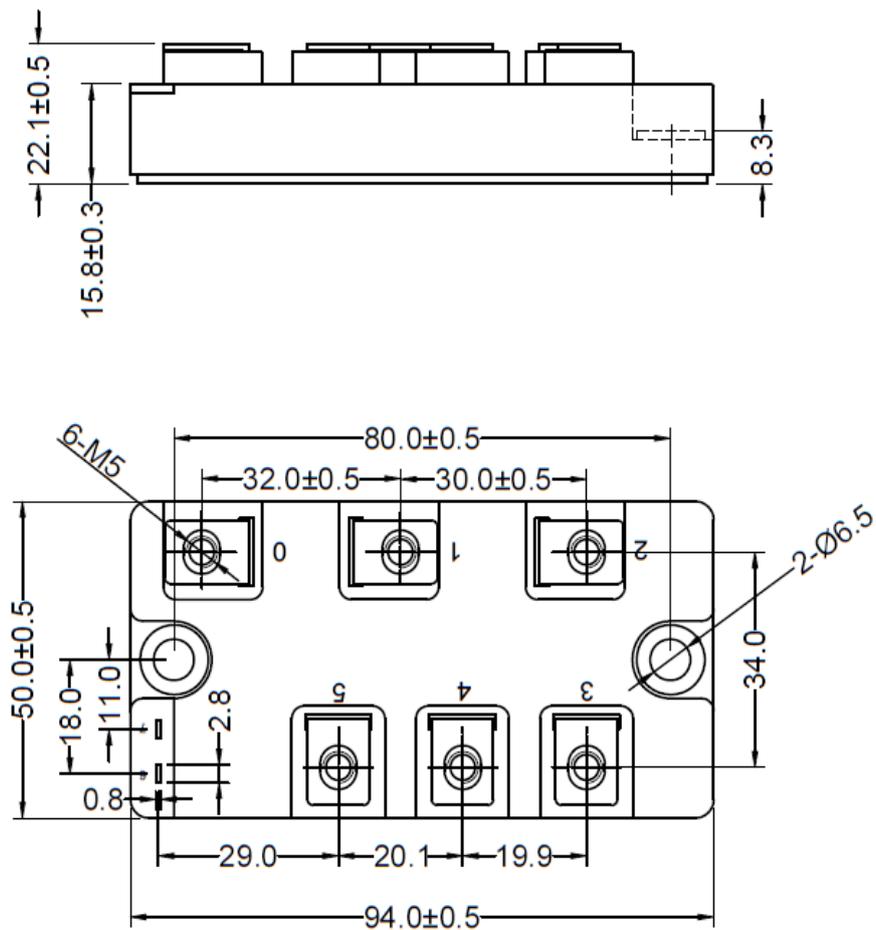


Figure 10. SCR Gate Characteristics



Dimensions in (mm)  
 Figure 11. Package Outline